

Other View
另一角度



Bonding Mechanism
& X-Y Axis Assemble
焊接装置
& X-Y轴传送装置



Template
模板



Pin and Model Change
定位销和模型改变

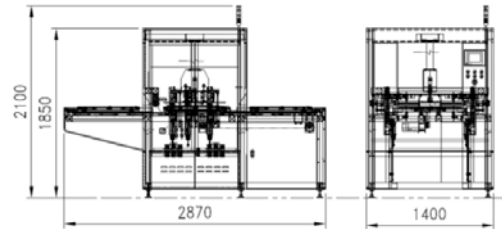
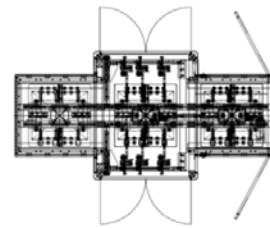
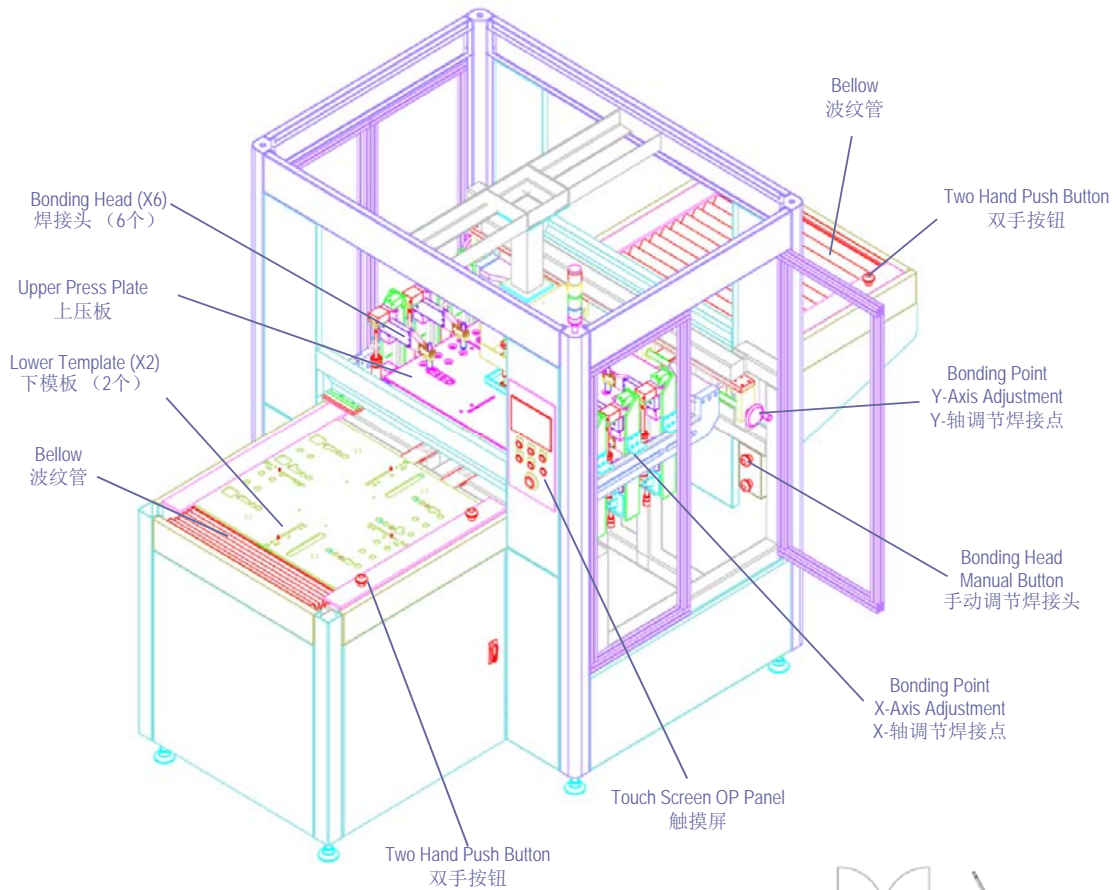
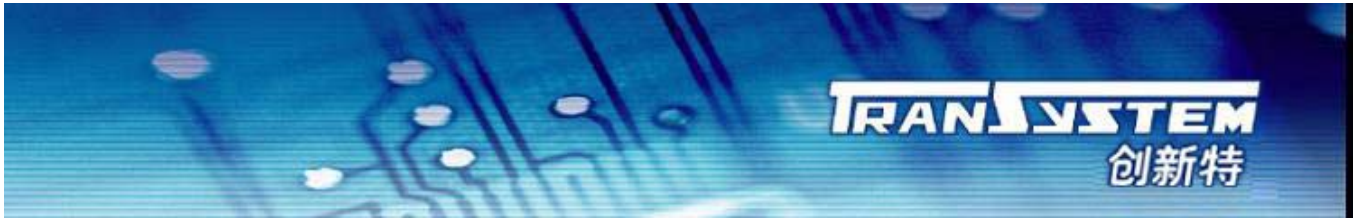
General Specifications/规格:

1. Board Size/板的尺寸: 510mm x 340mm (min)
622mm x 530mm (max)
2. Board Thickness/板的厚度: 0.5mm ~ 4.0mm
3. Machine Size/设备尺寸: 2870mm(L) x 1400mm(W) x

TS74255

TS74255 functions as bonding of several layers PCB and Prepreg. It has two load/unload positions that improves productivity. The bonding parameters of heating temperature, force and duration can be adjusted and data logged for quality checks and profiling.

TS74255的功能是将多层的PCB和半固化片焊接在一起。为了提高生产效率，该设备设有两个收/放板的位置。该设备可以调节焊接时的加热温度范围，压力和持续时间，也可以进行数据记录以便于产品的质量检测和分



Machine Specifications

Model	TS74255
Board Size	510mm x 340mm (min) ~ 622mm x 530mm (max)
Board Thickness	0.5-4.0mm
Working Height	980mm +/-30mm
Bond Head Temperature	400 °C (Max)
Air Supply	5-7 Bar
Template	Universal Template-2 units
No of Load/Unload Position	2 position
Board Bonding Side	both long and short sides
Power Supply	1PH, AC230V, 5KVA, 50Hz
Machine Size	2870mm(L) x 1400mm(W) x 1850mm(H)

Options

Panel Size	Customers' Requirement
Bonding Head	Customers' Requirement

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